

Remarks/Arguments:

Claims 1 and 13-14 are pending in the above-identified application. Claim 1 is rejected, and claims 13 and 14 are objected to. By the present Amendment, claim 1 is amended; claim 18 is canceled; and new claim 19 is presented for consideration. Claims 2-12 and 15-17 were previously canceled.

Election/Restrictions

The Office Action asserts that claim 18 is directed to an invention that is independent or distinct from the invention originally claimed. (See Office Action, page 2, item 1.) The Office Action withdraws claim 18 from consideration. (See Office Action, pages 2-3, item 2.) By the present Amendment, claim 18 is canceled.

Rejection of Claim 1 under 35 U.S.C. § 103

Claim 1 is rejected under 35 U.S.C. § 103(a) as being unpatentable over JP 2002-268577 of Kaneko et al. ("Kaneko") in view of U.S. Patent No. 6,496,373 to Chung and further in view of U.S. Patent Application Publication No. 2002/0193035 of Wei et al. ("Wei"). By the Amendment, claim 1 is amended. Support for these amendments may be found throughout the above-identified application, for example on page 7, line 17 through page 9, line 15 and in Fig. 4. No new matter has been added.

Applicant respectfully asserts that neither Kaneko, nor Chung, nor Wei, nor their combination discloses or suggests all of the features of amended claim 1, for example:

applying the adhesive to one of the panel and the holding plate, and **applying heat and pressure to the panel and the holding plate for forming a bulging-out portion of the adhesive bulging out from between the panel and the plate . . .** (Emphasis added.)

Support for these features may be found throughout the above-identified application, for example on page 8, lines 4-7; page 9, lines 9-12; and in Fig. 4. No new matter has been added.

1. Summary of an Embodiment of the Above-Identified Application

An embodiment described in the above-identified application uses a pull-to-remove adhesive 17 made of acrylic-based or silicon-based synthetic resin having good thermal conductivity. The adhesive 17 is applied to a panel 10 or a chassis 14 before they are combined. Then, heat and pressure are applied to the panel 10 and the chassis 14.

As pressure is applied to the adhesive 17 by pressing the panel 10 and the chassis 14 together, the adhesive 17 is squeezed, thereby causing it to expand its bonding area. A portion of the adhesive 17 is reserved in a groove 14B provided along the periphery of the chassis 14. The groove 14B prevents this portion of the adhesive 17 from bulging out beyond the periphery of the chassis 14. (See Application, page 8, lines 15-17.)

During the pressing operation, another portion of the adhesive 17 bulges out beyond the edges of the panel 10 and the chassis 14 to form one or more tabs 17A. (See Application, page 8, lines 4-7.) When the display is recycled, the tab 17A is pulled to provide for easily dismantling the display into separate panel 10 and chassis 14 components.

2. Summary of the References Relied upon in the Rejection

Kaneko discloses a plasma display panel (PDP) 1 that includes a front glass substrate 1A and a back glass substrate 1B. (See Kaneko, ¶ [0019].) A chassis 3 is secured to a back surface of the PDP 1 with a plurality of double-faced adhesive tapes 50. (See Kaneko, ¶ [0019].) An edge 50a of the double-faced adhesive tape 50 protrudes beyond the ends of the PDP 1 and chassis 3. (See Kaneko, ¶ [0020].)

Chung describes a heat dissipating arrangement that includes a heat dissipating element 20 and mechanical fasteners 30. (See Chung, Col. 3, lines 18-20, 38-39, and 49-50.) A plurality of components 10 are clamped by the mechanical fasteners 30. (See Chung, Col. 3, lines 48-50.) A melt-flowable thermal interface 100 is disposed between the components 10 and the heat dissipating element 20. (See Chung, Fig. 3.)

Wei describes a panel supply system that includes a panel 200 and a lamination plate 204. (See Wei, ¶¶ [0020]-[0021].) The lamination plate 204 includes a trench 206 formed at an edge thereof. (See Wei, ¶ [0021]). A sealing agent 208 is coated on an OEL display 202 between the panel 200 and the lamination plate 204. (See Wei, ¶ [0020].) A pressure is applied to the lamination plate 204, and the excess of the sealing agent 208 flows into the trench 206. (See Wei, ¶ [0022].) Wei describes that "the dimension of the sealing agent 208 is effectively controlled" by the trench 206. (See Wei, ¶ [0022].)

3. *The References, Alone or in Combination, Do Not Disclose or Suggest all of the Features of Claim 1*

As admitted in the Office Action, Kaneko is silent as to a method where adhesive is cured by simultaneous application of heat and pressure. (See Office Action, page 3, bottom through page 4, line 2.) As noted above, Kaneko uses double-faced adhesive tapes 50. Thus, Kaneko does not disclose or suggest "applying heat and pressure to the panel and the holding plate **for forming a bulging-out portion of the adhesive bulging out from between the panel and the plate,**" as recited in amended claim 1. (Emphasis added.)

As discussed above, Chung discloses a melt-flowable thermal interface 100 between a heat dissipating element 20 and components 10 attached to a plurality of fasteners 30. (See Chung, Col. 3, lines 40-50.) As can be seen in Fig. 3 of Chung, the melt-flowable thermal interface 100 is not bulging out from between the heat dissipating element 20 and the fasteners 30. Thus, Chung does not disclose or suggest "applying heat and pressure to the panel and the holding plate **for forming a bulging-out portion of the adhesive bulging out from between the panel and the plate,**" as recited in amended claim 1. (Emphasis added.)

Finally, Wei describes that the trench 206 effectively controls the dimension of the sealing agent 208. (See Wei, ¶ [0022].) As can be seen in Fig. 5 of Wei, the adhesive 208 is confined to a space between the grooves 206 between the panel 200 and the laminated board 204. The adhesive 208 is not bulging out from between the panel 200 and the laminated board 204. Thus, Wei does not disclose or suggest "applying heat and pressure to the panel and the holding plate **for forming a**

bulging-out portion of the adhesive bulging out from between the panel and the plate,” as recited in amended claim 1. (Emphasis added.)

In view of the foregoing, Applicant respectfully asserts that neither Kaneko, nor Chung, nor Wei, nor their combination discloses or suggests all of the above-quoted features of claim 1. Withdrawal of the rejection and reconsideration and allowance of claim 1 are respectfully requested.

Allowable Subject Matter

Claims 13 and 14 are objected to for being dependent upon a rejected base claim. The Office Action indicates that claims 13 and 14 would be allowable if rewritten into independent form including all of the limitations of claim 1. Applicant appreciates the indication of the allowability of the subject matter in claims 13 and 14, but because claim 1 is allowable for other reasons, Applicant does not amend claims 13 and 14 to include all of the limitations of claim 1.

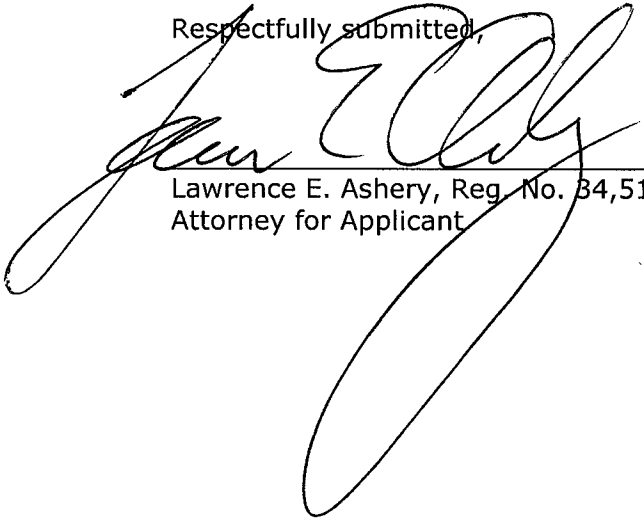
New Claim

By the present Amendment, Applicant submits a new claim 19 for consideration. New claim 19 depends from claim 1 and recites an additional step, namely “pulling the bulging-out portion to allow the panel to be removed from the holding plate.” As discussed above, neither Kaneko, nor Chung, nor Wei, nor their combination discloses or suggests the “bulging-out portion of the adhesive bulging out from between the panel and the plate,” as recited in claim 1. For reasons similar to those discussed above with respect to claim 1, neither Kaneko, nor Chung, nor Wei, nor their combination discloses or suggests “**pulling** the bulging-out portion to allow the panel to be removed from the holding plate,” as recited in new claim 19. (Emphasis added.) Favorable consideration is respectfully requested.

Conclusion

In view of the foregoing remarks and amendments, Applicant respectfully asserts that the claims are in condition for allowance, which action is respectfully requested.

Respectfully submitted,



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